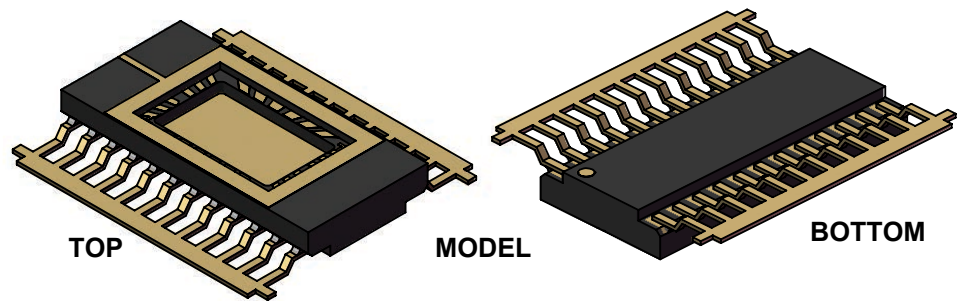
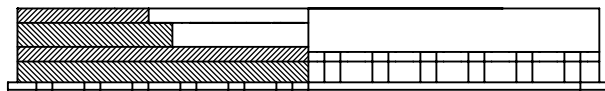


BRAZE: Ag-Cu
LEAD: ALLOY 42 OR KOVAR

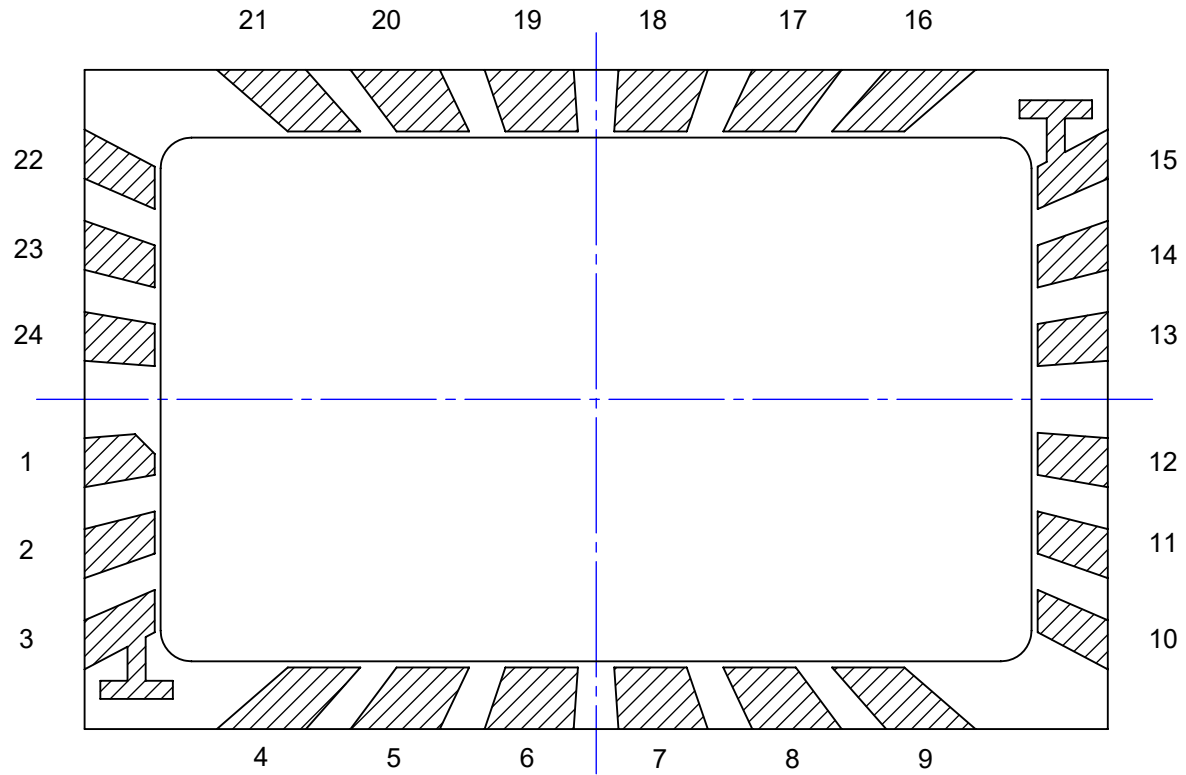


Notes: (Unless Otherwise Specified).

1. DIMENSIONS IN MM.
2. ALL EXPOSED METAL AND METALLIZED AREA SHALL BE GOLD PLATED.
3. 60 MICRO INCH MIN. THK. OVER NICKEL PLATED.
4. SEAL AREA AND DIE ATTACH AREA SHALL BE ISOLATED FROM ANY LEADS. (ZERO GROUND)

APPROVALS	DATE	TopLine®			
DRAWN T. Au	3/29/2022				
ENG M. Hart	3/29/2022	TITLE CSOP24G-N170x283 OPEN CERAMIC PACKAGE			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		6:1	A	162419	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 5
REVISED					

BONDING PADS



TopLine®

TITLE CSOP24G-N170x283
OPEN CERAMIC PACKAGE

SCALE	SIZE	DRAWING NO.	REV
16:1	A	162419	A

DO NOT SCALE DRAWING

SHEET 2 OF 5

**DIMENSION
CAVITY AND SEAL RING**

DESCRIPTION	REF.	DIMENSION INCH	DIMENSION MM
DIE CAVITY	DIE	0.161 x 0.283	4.32 x 7.19
BOND O.D.	BOND	0.215 x 0.333	5.45 x 8.45
SEAL RING I.D.	SR I.D.	0.215 x 0.333	5.45 x 8.45
SEAL RING O.D.	SR O.D.	0.285 x 0.404	7.24 x 10.26

TopLine®

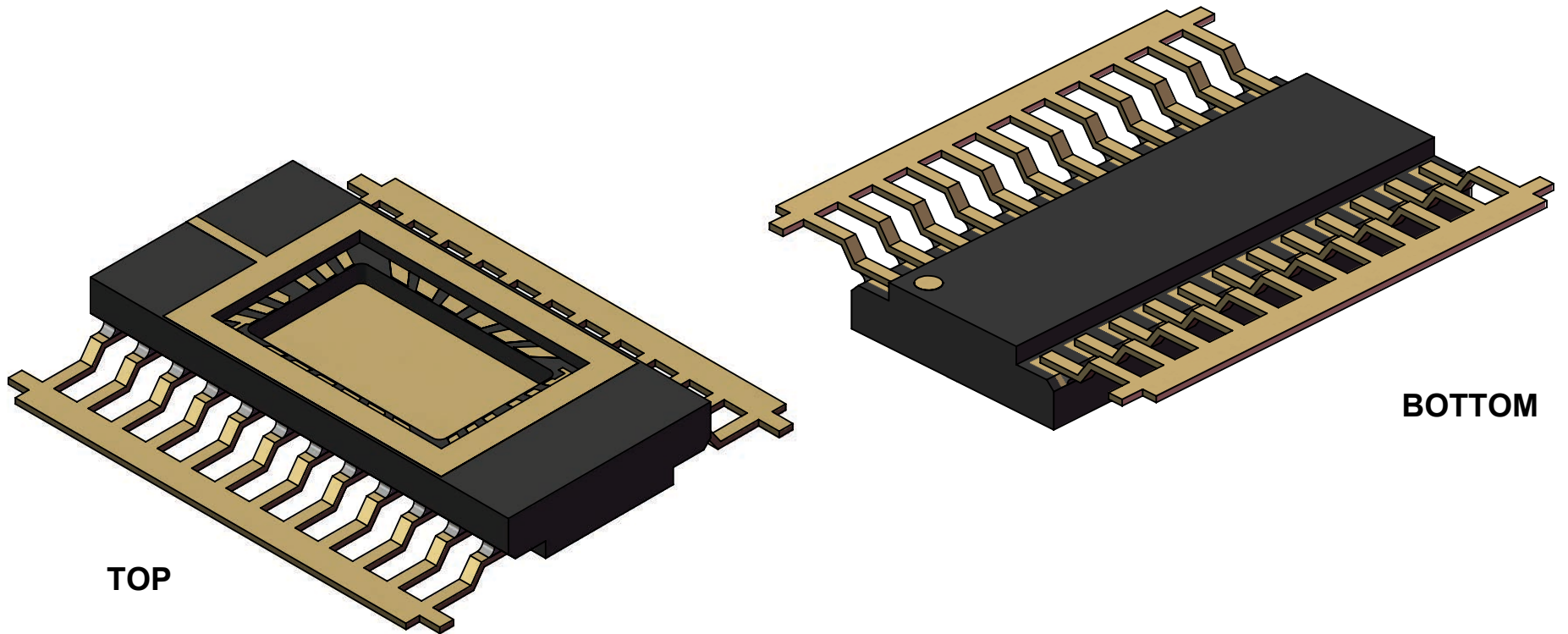
TITLE CSOP24G-N170x283
OPEN CERAMIC PACKAGE

SCALE NONE	SIZE A	DRAWING NO. 162419	REV A
---------------	-----------	-----------------------	----------

DO NOT SCALE DRAWING

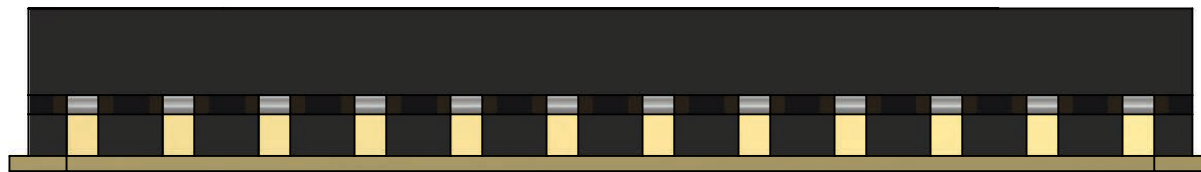
SHEET 3 OF 5

**MODELS
OPEN CAVITY**



TOP

BOTTOM



EDGE

TopLine®

TITLE CSOP24G-N170x283
OPEN CERAMIC PACKAGE

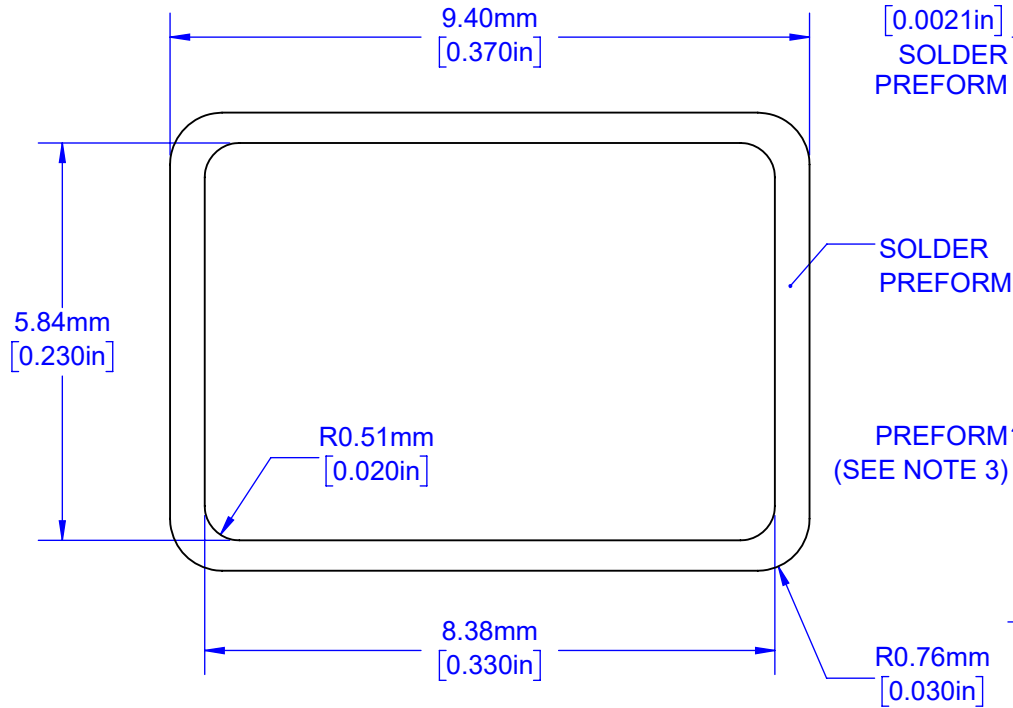
SCALE 6:1	SIZE A	DRAWING NO. 162419	REV A
--------------	-----------	-----------------------	----------

DO NOT SCALE DRAWING

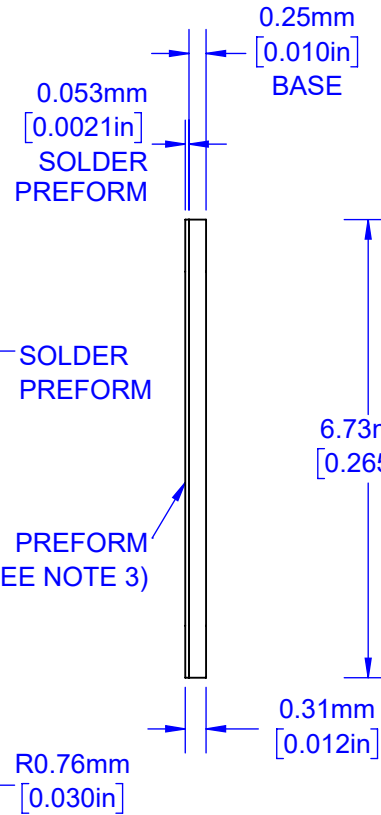
SHEET 4 OF 5

COMBO LID

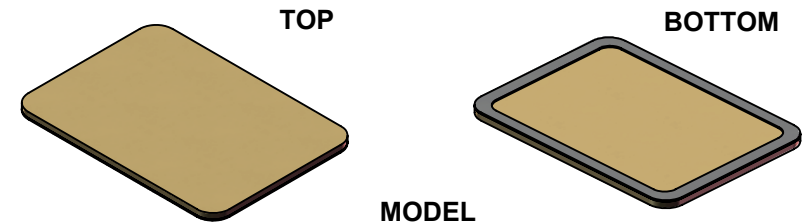
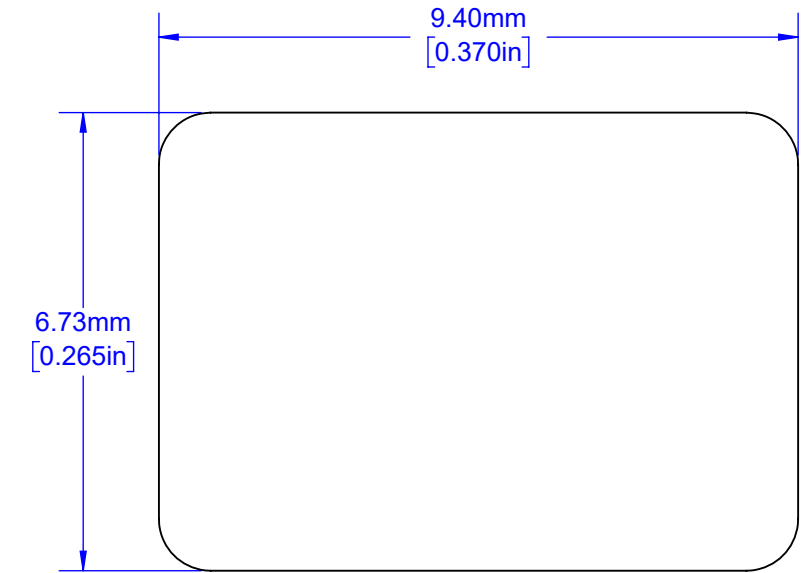
BOTTOM



SIDE



TOP



NOTES:

1. BASE MATERIAL: KOVAR or ALLOY 42.
2. PLATING: Ni 50~350 MICRO-INCH PER SIDE.
Au 25 MICRO-INCH MIN PER SIDE.
3. SOLDER PREFORM: Au 80% ±1.0 Sn 20%.
4. FLATNESS 1.0MIL (25µm) MAXIMUM PER 0.5-inch (12.7mm).

REF: HR-C-2191

TopLine®			
TITLE		CL-370x265-A COMBO LID	
SCALE	SIZE	DRAWING NO.	REV
9:1	A	163701	A
DO NOT SCALE DRAWING			SHEET 5 OF 5